



Material Content Data Sheet



Sales Product Name		SPB80P06P G		Issued		28. August 2013		
MA#		MA000723228						
Package		PG-TO263-3-2		Weight*		1466.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.978	0.82	0.82	8168	8168
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		582	
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174	
	non noble metal	copper	7440-50-8	851.691	58.06	58.14	580791	581547
wire	non noble metal	aluminium	7429-90-5	3.745	0.26	0.26	2554	2554
encapsulation	organic material	carbon black	1333-86-4	8.732	0.60		5955	
	plastics	epoxy resin	-	96.056	6.55		65503	
	inorganic material	silicondioxide	60676-86-0	477.370	32.55	39.70	325532	396990
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6585	6585
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156
solder	non noble metal	tin	7440-31-5	0.117	0.01		80	
	noble metal	silver	7440-22-4	0.147	0.01		100	
	non noble metal	lead	7439-92-1	5.602	0.38	0.40	3820	4000
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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